AMPLEON

Package outline

LGA-7x7-20-2 □ 0.100 C Terminal 1 **SECTION B-B** 7.00 index area **SCALE 80:1** -0.025 ± 0.010 (1) Cropped view В Section B-B Solder resist **Exposed metal** 0.100C-2x **DETAIL A** // 0.050 C -(0.98)SCALE 50:1 See detail A 0.98 С Ф 0.100 A ф 0.100 B 6.80 **-**0.42 (20x) 0.50 (20x) 10 5 **1**11 6.80 4.90 15 Terminal 1 -1.03 (16x) index area 4.90 Tolerances unless otherwise stated: 2 Revision: Package outline drawing: 30-Dec-19 Angle: ± 1° Revision date: Dimension: ± 0.10 units in mm. LGA-7x7-20-2 Third angle projection Sheet 1 of 2 **Publication**



Package outline

LGA-7x7-20-2

Drawing Notes	
Item	Description
1	Metal thickness of solder pads.
2	Flatness with respect to exposed metal

Package outline drawing:

LGA-7x7-20-2

units in mm.

Tolerances unless otherwise stated:

Dimension: ± 0.10

A

Angle: ± 1°

Revision:

Revision date: 30-Dec-19

2

Third angle projection

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